



National Standards Authority of Ireland

IRISH STANDARD

I.S. EN 62326-4:1998

ICS 31.180

PRINTED BOARDS

PART 4: RIGID MULTILAYER PRINTED

BOARDS WITH INTERLAYER CONNECTIONS

SECTIONAL SPECIFICATION

(IEC 2326-4:1996)

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 62326-4

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Descriptors: Printed boards, rigid multilayer, interlayer connections, capability approval, sectional specification

English version

Printed boards
Part 4: Rigid multilayer printed boards with interlayer connections
Sectional specification
(IEC 2326-4:1996)

Cartes imprimées
Partie 4: Cartes imprimées multicouches
rigides avec connexions intercouches
Spécification intermédiaire
(CEI 2326-4:1996)

Leiterplatten
Teil 4: Starre Mehrlagen-Leiterplatten
mit Durchverbindungen
Rahmenspezifikation
(IEC 2326-4:1996)

This European Standard was approved by CENELEC on 1996-12-09. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 52/655/FDIS, future edition 1 of IEC 2326-4, prepared by IEC TC 52, Printed circuits, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62326-4 on 1996-12-09.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 1997-09-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) -

This part 4 is to be used in conjunction with EN 62326-1:1997 and EN 62326-4-1:1997.

Annexes designated "normative" are part of the body of the standard.

Annexes designated "informative" are given for information only.

In this standard, annex ZA is normative and annexes A, B and C are informative.

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 2326-4:1996 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)**Normative references to international publications
with their corresponding European publications**

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE: When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 68-2-3	1969	Basic environmental testing procedures Part 2: Tests - Test Ca: Damp heat, steady state	HD 323.2.3 S2 ¹⁾	1987
IEC 68-2-20	1979	Test T: Soldering	HD 323.2.20 S3 ²⁾	1988
IEC 68-2-38	1974	Test Z/AD: Composite temperature/humidity cyclic test	HD 323.2.38 S1	1988
IEC 1189-3	³⁾	Test methods for electrical materials, interconnection structures and assemblies Part 3: Test methods for interconnection structures (printed boards)	-	-
IEC 1249-5-1	1995	Materials for interconnection structures Part 5: Sectional specification set for conductive foils and films with and without coatings -- Section 1: Copper foils (for the manufacture of copper-clad base materials)	EN 61249-5-1	1996
IEC 2326-1	1996	Printed boards Part 1: Generic specification	EN 62326-1	1997
IEC 2326-4-1	1996	Part 4: Rigid multilayer printed boards with interlayer connections Sectional specification Section 1: Capability Detail Specification Performance levels A, B and C	EN 62326-4-1	1997
QC 001002	1986	Rules of procedure of the IEC Quality Assessment System for Electronic Components (IECQ)	-	-

1) HD 323.2.3 S2 includes A1:1984 to IEC 68-2-3.

2) HD 323.2.20 S3 includes A2:1987 to IEC 68-2-20.

3) At present under IEC-CENELEC parallel vote (52/627/FDIS).

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